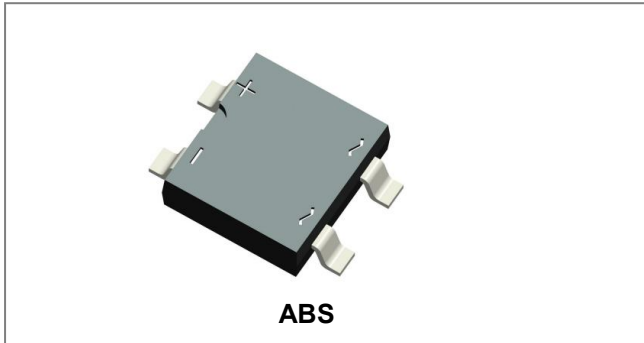


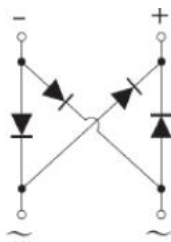
EABS21 THRU EABS26
SINGLE PHASE 2AMP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER



Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: SOPA-4, Molded plastic ABS
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting Position: Any
- Weight: 0.101 grams(approx)
-

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

| Type Number | Symbol | EABS21 | EABS22 | EABS24 | EABS26 | Units |
|--|------------------------------------|--------|--------|--------|--------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_{DC} | 100 | 200 | 400 | 600 | V |
| RMS Reverse Voltage | V_{RMS} | 70 | 140 | 280 | 420 | V |
| Average Rectified Output Current @T _C =100°C | $I_{(AV)}$ | 2.0 | | | | V |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 60 | | | | A |
| Rating for fusing (t<8.3ms) | I^2t | 14.94 | | | | A ² s |

Electrical Characteristics@T_A=25°C unless otherwise specified

| Type Number | Symbol | EABS21 | EABS22 | EABS24 | EABS26 | Units |
|---|-----------------|------------|--------|--------|--------|-------|
| Maximum Forward Voltage (per element) @I _F =2A | V _F | 0.95 | | 1.25 | 1.70 | V |
| Maximum Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 125°C | I _R | 5.0 500 | | | | μA |
| Maximum Reverse Recovery Time (Note 1) | T _{rr} | 35 | | | | ns |

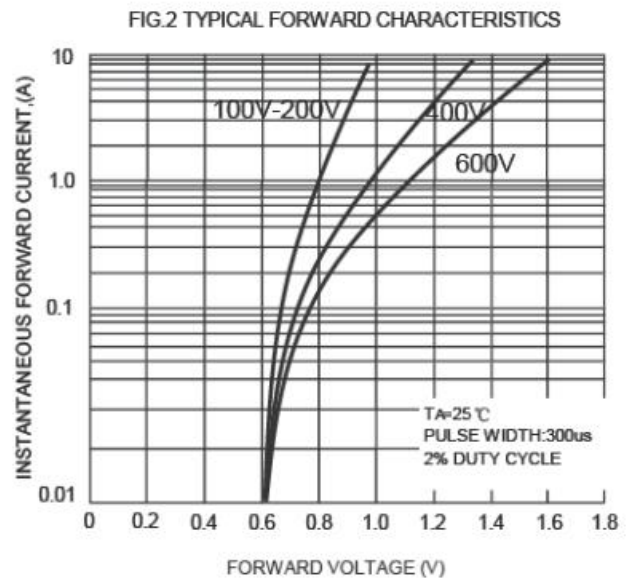
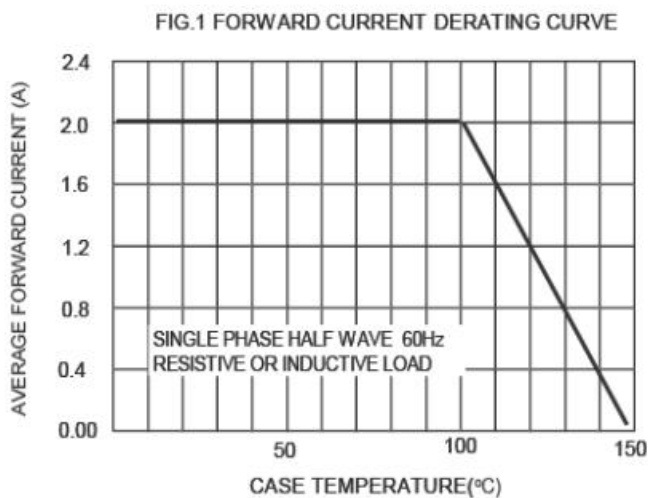
* Pulse width < 300 μs, duty cycle < 2%

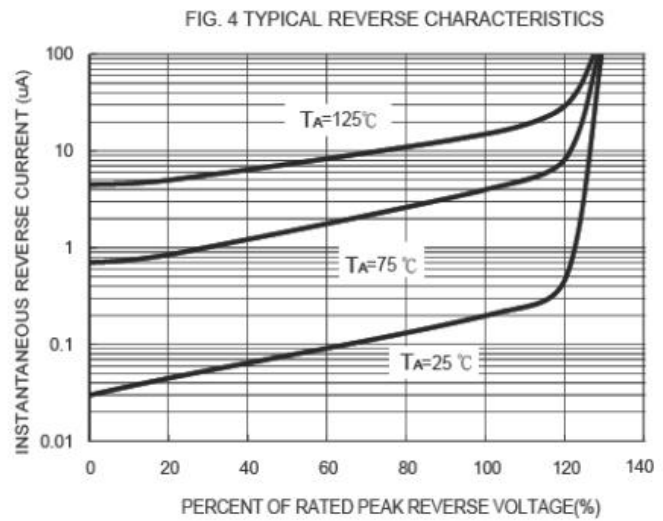
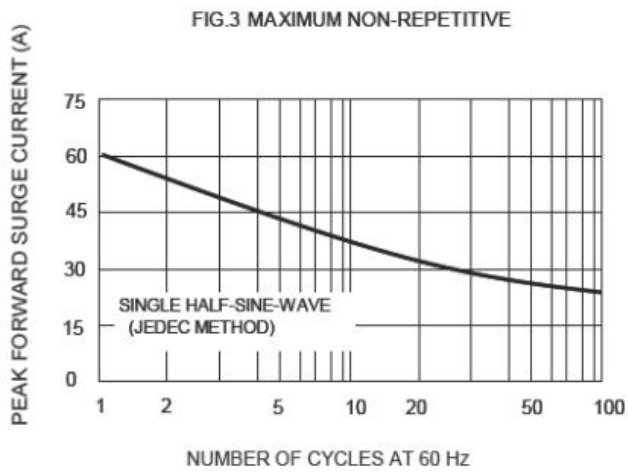
Thermal-Mechanical Specifications@T_A=25°C unless otherwise specified

| Type Number | Symbol | EABS21 | EABS22 | EABS24 | EABS26 | Units |
|---|--------------------------------------|-------------|--------|--------|--------|-------|
| Typical Thermal Resistance | R _{θJA} R _{θJL} | 62.5 25 | | | | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | | | | °C |

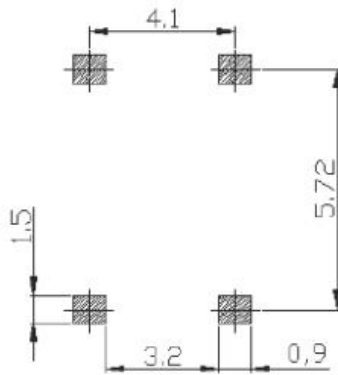
Note:1. Reverse Recovery Test Conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A

Ratings and Characteristics Curves





ABS PAD LAYOUT



Ordering Information

| Device | Package | Plating | Shipping |
|--------------------------|------------------|---------|----------------|
| EABS21 THRU EABS26 | ABS (Pb-Free) | Pure Sn | 5000pcs / reel |

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

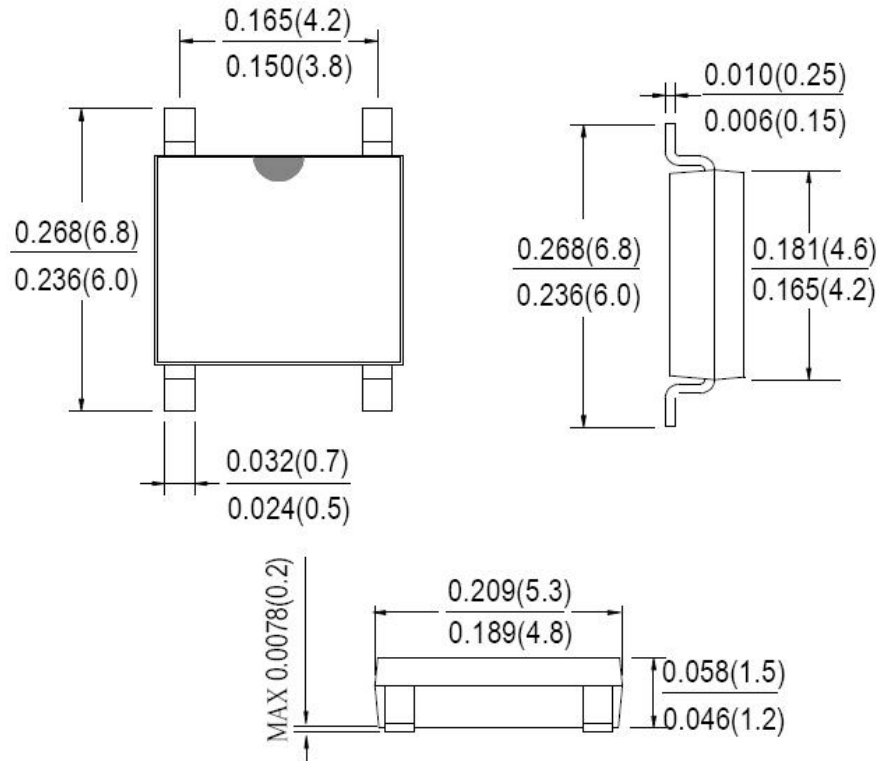


Where XXXXX is YYWWL

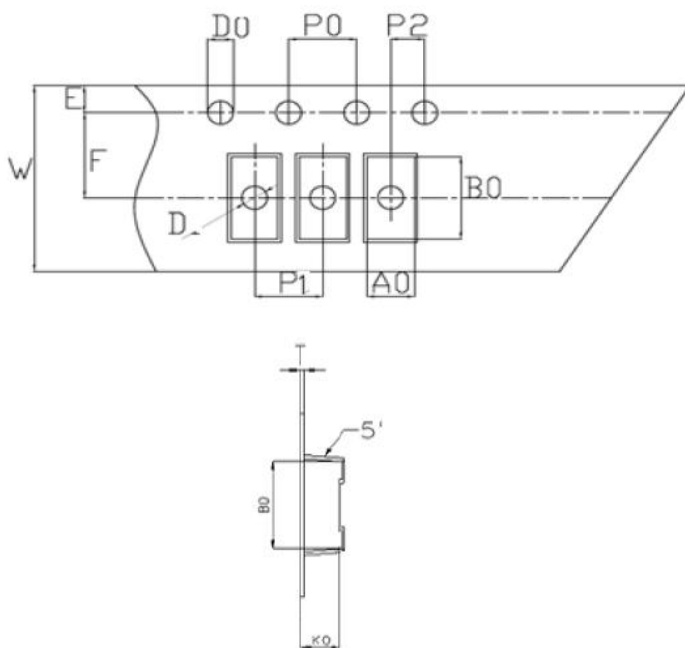
EABS21 = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Mechanical Dimensions ABS(Inches/Millimeters)



Carrier Tape Specification ABS



| SYMBOL | Millimeters | |
|--------|-------------|-------|
| | Min. | Max. |
| A0 | 5.21 | 5.41 |
| B0 | 7.10 | 7.30 |
| D0 | 1.50 | 1.60 |
| D1 | 1.40 | 1.60 |
| P0 | 3.90 | 4.10 |
| P1 | 7.90 | 8.10 |
| P2 | 1.95 | 2.05 |
| E | 1.65 | 1.85 |
| K0 | 1.55 | 1.75 |
| F | 5.45 | 5.55 |
| W | 11.90 | 12.10 |
| T | 0.24 | 0.30 |
| 10P0 | 39.80 | 40.20 |

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